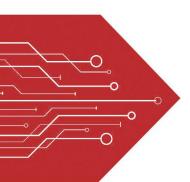
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet





SOD-523



BAT54X Schottky Barrier Diode

FEATURES

- Extremely Fast Switching Speed
- Low Forward Voltage

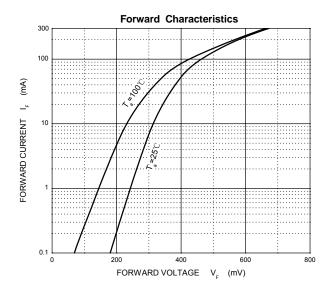
Maximum Ratings @Ta=25℃

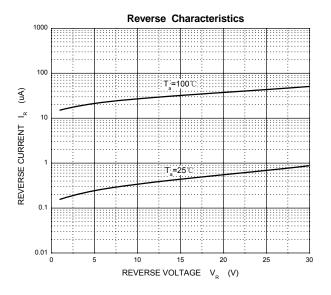
Parameter	Symbol	Limit	Unit
Non-repetitive peak reverse voltage	V_{RM}	30	V
DC blocking voltage	V _R	21	V
Average rectified output current	Io	100	mA
Forward continuous current	I _F	200	mA
Repetitive peak forward current	I _{FRM}	300	mA
Bcb!fYdYljlij Y'DYU_'Forward surge current 4 hi, " a g	I _{FSM}	600	mA
Power dissipation	Pd	150	mW
Thermal resistance junction to ambient	R ₀ JA	667	°C/W
Junction temperature	TJ	125	°C
Storage temperature range	T _{STG}	-55~+150	$^{\circ}$

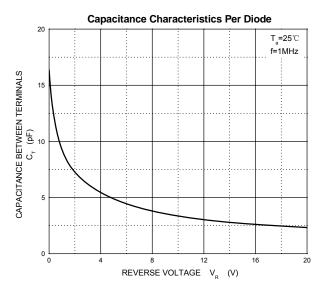
Electrical Characteristics @Ta=25°C

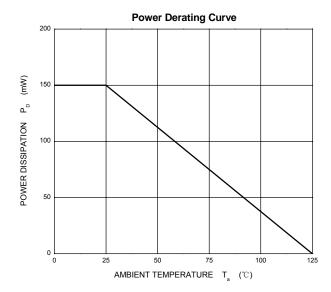
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse breakdown voltage	V (BR)	I _R =100μA	30			V
	V _{F1}	I _F =0.1mA			240	mV
	V _{F2}	I _F =1.0mA			320	mV
Forward voltage	V _{F3}	I _F =10mA			400	mV
	V _{F4}	I _F =30mA			500	mV
	V _{F5}	I _F =100mA			1000	mV
Reverse current	I _R	V _R =25V			2.0	uA
Reverse recovery time	t _{rr}	I_F =10mA, I_R =10mA to 1mA , R_L =100 Ω		5.0	ns	
Capacitance between terminals	Ст	V _R =1V,f=1MHz			10	pF





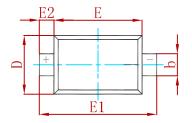


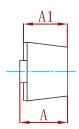


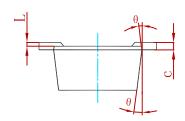




PACKAGE MECHANICAL DATA

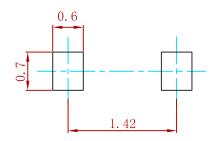






	Dimensions	In Millimatara	Dimension	a la lachea	
Symbol	Dimensions In Millimeters		Dimensions In Inches		
Cymbol	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200	REF	0.008	REF	
L	0.010	0.070	0.001	0.003	
θ	7° F	REF	7° F	REF	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
 3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAT54X	SOD-523	3000



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